TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN# 20150511000
Qualification of NSE as Additional Assembly Site for Select VQFN package device
Change Notification / Sample Request

Date: 5/14/2015
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150511000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC1101RGP	null
CC1101RGPR	null
CC1101RGPT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150511000	**PCN Date:**	05/14/2015
Title:	Qualification of NSE as Additional Assembly Site for Select VQFN package device		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	08/14/2015	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒ Assembly Site	☐ Design	☐ Wafer Bump Site
☐ Assembly Process	☐ Data Sheet	☐ Wafer Bump Material
☐ Assembly Materials	☐ Part number change	☐ Wafer Bump Process
☐ Mechanical Specification	☐ Test Site	☐ Wafer Fab Site
☐ Packing/Shipping/Labeling	☐ Test Process	☐ Wafer Fab Materials
		☐ Wafer Fab Process

PCN Details

Description of Change:

Qualification of NSE as Additional Assembly Site for Select VQFN package device. Assembly differences are shown in the following table:

	TI Clark	NSE
Mount Compound	4207123	PZ0031
Wire	4218107 (0.8 Mil Cu)	GZ0017 (1.0 Mil Au)
Lead finish	NiPdAu	NiPdAuAg

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB
NSE Thailand	Assembly Site Origin (22L)	ASO: NSE

Sample product shipping label (not actual product label)

MADE IN: Malaysia
2DC:
2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: TI-Clark = I, NSE =J

Product Affected:

CC1101RGP	CC1101RGPR	CC1101RGPT	TLMW301RGPR

Qualification Report

Product Attributes

Attributes	Qual Device: CC1101RGP	Supporting QBS: TLV320AIC3254RHB	Supporting QBS: CC1101RGP
Assembly Site	UTAC/NSE	UTAC/NSE	UTAC/NSE
Package Family	QFN	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL94V-0
Die Attributes			
Wafer Fab Site	TSMC FAB 4	DMOS5	TSMC FAB 4
Wafer Fab Process	0.18UM-TSMC	1833C05	0.18UM-TSMC
Package Attributes			
Package Designator	RGP	RHB	RGP
Package Size (mils)	157.48 X 157.48	196.85 X 196.85	157.48 X 157.48
Body Thickness (mils)	39.37	35.43	39.37
Pin Count	20	32	20
Lead Frame Material	Cu	Cu	Cu
Lead Finish	NiPdAuAg	NiPdAu	NiPdAu
Mount Compound	PZ0031	PZ0031	PZ0031
Mold Compound	CZ0142	CZ0142	CZ0142
Green Status	Qualified Pb-free(SMT) and Green	Qualified Pb-free(SMT) and Green	Qualified Pb-free(SMT) and Green
Bond Wire Composition	Au	Au	Au
Bond Wire Diameter (mils)	1.0	1.0	1.0
Flammability Rating	UL 94 V-0	UL 94 V-0	UL94V-0

- QBS: Qual By Similarity
- Qual Device CC1101RGP is qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC1101RGP	Supporting QBS: TLV320AIC3254RHB	Supporting QBS: CC1101RGP
AC	Autoclave	121C, 100%RH/96 hours	-	-	1/75/0
TC	Temperature Cycle	-65/150C/500 cycles	-	-	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/3/0	-	-
MSL	Moisture Sensitivity, JEDEC	Level 3-260C	3/36/0	1/12/0	-

- Preconditioning was performed for Autoclave, Temperature Cycle, as applicable

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com